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Understanding [Embedded - FPGAs \(Field Programmable Gate Array\)](#)

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

Details

Product Status	Obsolete
Number of LABs/CLBs	23780
Number of Logic Elements/Cells	504000
Total RAM Bits	27695104
Number of I/O	704
Number of Gates	-
Voltage - Supply	1.07V ~ 1.13V
Mounting Type	Surface Mount
Operating Temperature	0°C ~ 85°C (TJ)
Package / Case	1517-BBGA
Supplier Device Package	1517-FBGA (40x40)
Purchase URL	https://www.e-xfl.com/product-detail/intel/5agxfb7k6f40c6n

Symbol	Description	Minimum	Maximum	Unit
V _{CCPLL_HPS}	HPS PLL analog power supply	–0.50	3.25	V
V _{CC_AUX_SHARED}	HPS auxiliary power supply	–0.50	3.25	V
I _{OUT}	DC output current per pin	–25	40	mA
T _J	Operating junction temperature	–55	125	°C
T _{STG}	Storage temperature (no bias)	–65	150	°C

Maximum Allowed Overshoot and Undershoot Voltage

During transitions, input signals may overshoot to the voltage listed in the following table and undershoot to –2.0 V for input currents less than 100 mA and periods shorter than 20 ns.

The maximum allowed overshoot duration is specified as a percentage of high time over the lifetime of the device. A DC signal is equivalent to 100% duty cycle.

For example, a signal that overshoots to 4.00 V can only be at 4.00 V for ~15% over the lifetime of the device; for a device lifetime of 10 years, this amounts to 1.5 years.

Table 1-2: Maximum Allowed Overshoot During Transitions for Arria V Devices

This table lists the maximum allowed input overshoot voltage and the duration of the overshoot voltage as a percentage of device lifetime.

Symbol	Description	Condition	Minimum ⁽⁷⁾	Typical	Maximum ⁽⁷⁾	Unit
$V_{CCPD_HPS}^{(8)}$	HPS I/O pre-driver power supply	3.3 V	3.135	3.3	3.465	V
		3.0 V	2.85	3.0	3.15	V
		2.5 V	2.375	2.5	2.625	V
V_{CCIO_HPS}	HPS I/O buffers power supply	3.3 V	3.135	3.3	3.465	V
		3.0 V	2.85	3.0	3.15	V
		2.5 V	2.375	2.5	2.625	V
		1.8 V	1.71	1.8	1.89	V
		1.5 V	1.425	1.5	1.575	V
		1.35 V ⁽⁹⁾	1.283	1.35	1.418	V
$V_{CCRSTCLK_HPS}$	HPS reset and clock input pins power supply	3.3 V	3.135	3.3	3.465	V
		3.0 V	2.85	3.0	3.15	V
		2.5 V	2.375	2.5	2.625	V
		1.8 V	1.71	1.8	1.89	V
V_{CCPLL_HPS}	HPS PLL analog voltage regulator power supply	—	2.375	2.5	2.625	V

⁽⁷⁾ The power supply value describes the budget for the DC (static) power supply tolerance and does not include the dynamic tolerance requirements. Refer to the PDN tool for the additional budget for the dynamic tolerance requirements.

⁽⁸⁾ V_{CCPD_HPS} must be 2.5 V when V_{CCIO_HPS} is 2.5, 1.8, 1.5, or 1.2 V. V_{CCPD_HPS} must be 3.0 V when V_{CCIO_HPS} is 3.0 V. V_{CCPD_HPS} must be 3.3 V when V_{CCIO_HPS} is 3.3 V.

⁽⁹⁾ V_{CCIO_HPS} 1.35 V is supported for HPS row I/O bank only.

I/O Pin Leakage Current

Table 1-6: I/O Pin Leakage Current for Arria V Devices

Symbol	Description	Condition	Min	Typ	Max	Unit
I_I	Input pin	$V_I = 0\text{ V to }V_{CCIOMAX}$	-30	—	30	μA
I_{OZ}	Tri-stated I/O pin	$V_O = 0\text{ V to }V_{CCIOMAX}$	-30	—	30	μA

Bus Hold Specifications

Table 1-7: Bus Hold Parameters for Arria V Devices

The bus-hold trip points are based on calculated input voltages from the JEDEC standard.

Parameter	Symbol	Condition	V _{CCIO} (V)												Unit
			1.2		1.5		1.8		2.5		3.0		3.3		
			Min	Max	Min	Max	Min	Max	Min	Max	Min	Max	Min	Max	
Bus-hold, low, sustaining current	I _{SUSL}	V _{IN} > V _{IL} (max)	8	—	12	—	30	—	50	—	70	—	70	—	μA
Bus-hold, high, sustaining current	I _{SUSH}	V _{IN} < V _{IH} (min)	−8	—	−12	—	−30	—	−50	—	−70	—	−70	—	μA
Bus-hold, low, overdrive current	I _{ODL}	0 V < V _{IN} < V _{CCIO}	—	125	—	175	—	200	—	300	—	500	—	500	μA
Bus-hold, high, overdrive current	I _{ODH}	0 V < V _{IN} < V _{CCIO}	—	−125	—	−175	—	−200	—	−300	—	−500	—	−500	μA

I/O Standard	V_{CCIO} (V)			$V_{SWING(DC)}$ (V)		$V_{X(AC)}$ (V)			$V_{SWING(AC)}$ (V)	
	Min	Typ	Max	Min	Max	Min	Typ	Max	Min	Max
SSTL-125	1.19	1.25	1.31	0.18	⁽¹⁵⁾	$V_{CCIO}/2 - 0.15$	$V_{CCIO}/2$	$V_{CCIO}/2 + 0.15$	$2(V_{IH(AC)} - V_{REF})$	$2(V_{IL(AC)} - V_{REF})$

Differential HSTL and HSUL I/O Standards

Table 1-18: Differential HSTL and HSUL I/O Standards for Arria V Devices

I/O Standard	V_{CCIO} (V)			$V_{DIF(DC)}$ (V)		$V_{X(AC)}$ (V)			$V_{CM(DC)}$ (V)			$V_{DIF(AC)}$ (V)	
	Min	Typ	Max	Min	Max	Min	Typ	Max	Min	Typ	Max	Min	Max
HSTL-18 Class I, II	1.71	1.8	1.89	0.2	—	0.78	—	1.12	0.78	—	1.12	0.4	—
HSTL-15 Class I, II	1.425	1.5	1.575	0.2	—	0.68	—	0.9	0.68	—	0.9	0.4	—
HSTL-12 Class I, II	1.14	1.2	1.26	0.16	$V_{CCIO} + 0.3$	—	$0.5 \times V_{CCIO}$	—	$0.4 \times V_{CCIO}$	$0.5 \times V_{CCIO}$	$0.6 \times V_{CCIO}$	0.3	$V_{CCIO} + 0.48$
HSUL-12	1.14	1.2	1.3	0.26	0.26	$0.5 \times V_{CCIO} - 0.12$	$0.5 \times V_{CCIO}$	$0.5 \times V_{CCIO} + 0.12$	$0.4 \times V_{CCIO}$	$0.5 \times V_{CCIO}$	$0.6 \times V_{CCIO}$	0.44	0.44

Differential I/O Standard Specifications

Table 1-19: Differential I/O Standard Specifications for Arria V Devices

Differential inputs are powered by V_{CCPD} which requires 2.5 V.

Transceiver Specifications for Arria V GT and ST Devices

Table 1-26: Reference Clock Specifications for Arria V GT and ST Devices

Symbol/Description	Condition	Transceiver Speed Grade 3			Unit
		Min	Typ	Max	
Supported I/O standards	1.2 V PCML, 1.4 VPCML, 1.5 V PCML, 2.5 V PCML, Differential LVPECL ⁽⁴⁰⁾ , HCSL, and LVDS				
Input frequency from REFCLK input pins	—	27	—	710	MHz
Rise time	Measure at ±60 mV of differential signal ⁽⁴¹⁾	—	—	400	ps
Fall time	Measure at ±60 mV of differential signal ⁽⁴¹⁾	—	—	400	ps
Duty cycle	—	45	—	55	%
Peak-to-peak differential input voltage	—	200	—	300 ⁽⁴²⁾ /2000	mV
Spread-spectrum modulating clock frequency	PCI Express (PCIe)	30	—	33	kHz
Spread-spectrum downspread	PCIe	—	0 to –0.5%	—	—
On-chip termination resistors	—	—	100	—	Ω
V _{ICM} (AC coupled)	—	—	1.2	—	V
V _{ICM} (DC coupled)	HCSL I/O standard for the PCIe reference clock	250	—	550	mV

⁽⁴⁰⁾ Differential LVPECL signal levels must comply to the minimum and maximum peak-to-peak differential input voltage specified in this table.⁽⁴¹⁾ REFCLK performance requires to meet transmitter REFCLK phase noise specification.⁽⁴²⁾ The maximum peak-to peak differential input voltage of 300 mV is allowed for DC coupled link.

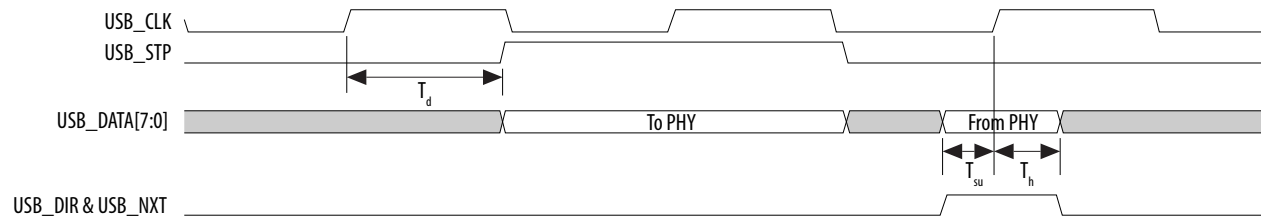
Symbol	Parameter	Condition	Min	Typ	Max	Unit
$f_{\text{OUT_EXT}}$	Output frequency for external clock output	–3 speed grade	—	—	670 ⁽⁶³⁾	MHz
		–4 speed grade	—	—	670 ⁽⁶³⁾	MHz
		–5 speed grade	—	—	622 ⁽⁶³⁾	MHz
		–6 speed grade	—	—	500 ⁽⁶³⁾	MHz
t_{OUTDUTY}	Duty cycle for external clock output (when set to 50%)	—	45	50	55	%
t_{FCOMP}	External feedback clock compensation time	—	—	—	10	ns
$t_{\text{DYCONFIGCLK}}$	Dynamic configuration clock for <code>mgmt_clk</code> and <code>scanclk</code>	—	—	—	100	MHz
t_{LOCK}	Time required to lock from end-of-device configuration or deassertion of <code>areset</code>	—	—	—	1	ms
t_{DLOCK}	Time required to lock dynamically (after switchover or reconfiguring any non-post-scale counters/delays)	—	—	—	1	ms
f_{CLBW}	PLL closed-loop bandwidth	Low	—	0.3	—	MHz
		Medium	—	1.5	—	MHz
		High ⁽⁶⁴⁾	—	4	—	MHz
$t_{\text{PLL_PSERR}}$	Accuracy of PLL phase shift	—	—	—	±50	ps
t_{ARESET}	Minimum pulse width on the <code>areset</code> signal	—	10	—	—	ns
$t_{\text{INCCJ}}^{(65)(66)}$	Input clock cycle-to-cycle jitter	$F_{\text{REF}} \geq 100 \text{ MHz}$	—	—	0.15	UI (p-p)
		$F_{\text{REF}} < 100 \text{ MHz}$	—	—	±750	ps (p-p)

⁽⁶⁴⁾ High bandwidth PLL settings are not supported in external feedback mode.⁽⁶⁵⁾ A high input jitter directly affects the PLL output jitter. To have low PLL output clock jitter, you must provide a clean clock source with jitter < 120 ps.⁽⁶⁶⁾ F_{REF} is f_{IN}/N , specification applies when $N = 1$.

Symbol	Description	Min	Max	Unit
T_h	SPI MISO hold time	1	—	ns
$T_{\text{duty cycle}}$	SPI_CLK duty cycle	45	55	%
T_{dssfrst}	Output delay SPI_SS valid before first clock edge	8	—	ns
T_{dsslst}	Output delay SPI_SS valid after last clock edge	8	—	ns
T_{dio}	Master-out slave-in (MOSI) output delay	–1	1	ns

⁽⁸⁶⁾ This value is based on $\text{rx_sample_dly} = 1$ and $\text{spi_m_clk} = 120$ MHz. spi_m_clk is the internal clock that is used by SPI Master to derive its SCLK_OUT . These timings are based on rx_sample_dly of 1. This delay can be adjusted as needed to accommodate slower response times from the slave. Note that a delay of 0 is not allowed. The setup time can be used as a reference starting point. It is very crucial to do a calibration to get the correct rx_sample_dly value because each SPI slave device may have different output delay and each application board may have different path delay. For more information about rx_sample_delay , refer to the SPI Controller chapter in the Hard Processor System Technical Reference Manual.

Figure 1-12: USB Timing Diagram

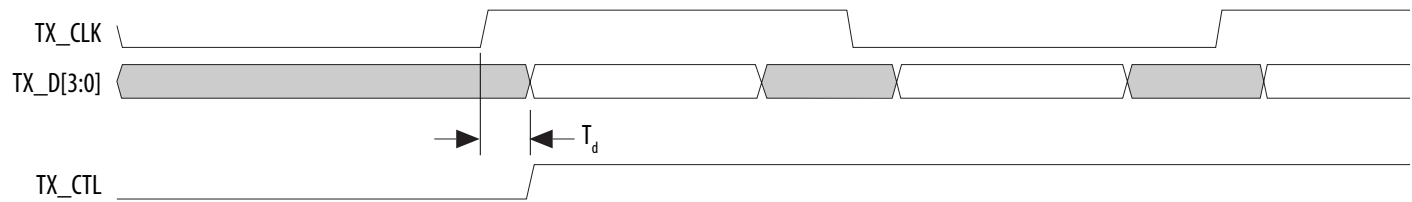


Ethernet Media Access Controller (EMAC) Timing Characteristics

Table 1-56: Reduced Gigabit Media Independent Interface (RGMII) TX Timing Requirements for Arria V Devices

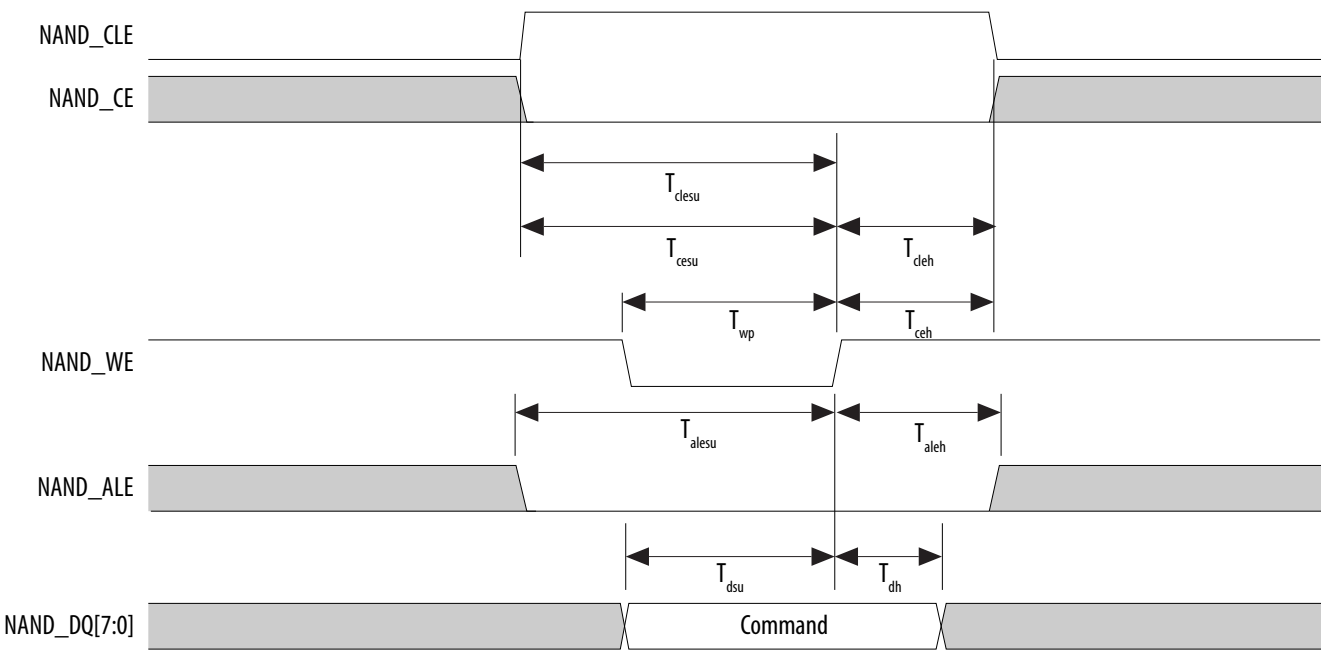
Symbol	Description	Min	Typ	Max	Unit
T_{clk} (1000Base-T)	TX_CLK clock period	—	8	—	ns
T_{clk} (100Base-T)	TX_CLK clock period	—	40	—	ns
T_{clk} (10Base-T)	TX_CLK clock period	—	400	—	ns
$T_{duty cycle}$	TX_CLK duty cycle	45	—	55	%
T_d	TX_CLK to TXD/TX_CTL output data delay	-0.85	—	0.15	ns

Figure 1-13: RGMII TX Timing Diagram



Symbol	Description	Min	Max	Unit
$T_{dh}^{(89)}$	Data to write enable hold time	5	—	ns
T_{cea}	Chip enable to data access time	—	25	ns
T_{rea}	Read enable to data access time	—	16	ns
T_{rhz}	Read enable to data high impedance	—	100	ns
T_{rr}	Ready to read enable low	20	—	ns

Figure 1-17: NAND Command Latch Timing Diagram



FPP Configuration Timing

DCLK-to-DATA[] Ratio (r) for FPP Configuration

Fast passive parallel (FPP) configuration requires a different DCLK-to-DATA[] ratio when you turn on encryption or the compression feature.

Depending on the DCLK-to-DATA[] ratio, the host must send a DCLK frequency that is r times the DATA[] rate in byte per second (Bps) or word per second (Wps). For example, in FPP $\times 16$ where the r is 2, the DCLK frequency must be 2 times the DATA[] rate in Wps.

Table 1-65: DCLK-to-DATA[] Ratio for Arria V Devices

Configuration Scheme	Encryption	Compression	DCLK-to-DATA[] Ratio (r)
FPP (8-bit wide)	Off	Off	1
	On	Off	1
	Off	On	2
	On	On	2
FPP (16-bit wide)	Off	Off	1
	On	Off	2
	Off	On	4
	On	On	4

FPP Configuration Timing when DCLK-to-DATA[] = 1

When you enable decompression or the design security feature, the DCLK-to-DATA[] ratio varies for FPP $\times 8$ and FPP $\times 16$. For the respective DCLK-to-DATA[] ratio, refer to the DCLK-to-DATA[] Ratio for Arria V Devices table.

Table 1-66: FPP Timing Parameters When DCLK-to-DATA[] Ratio is 1 for Arria V Devices

Symbol	Parameter	Minimum	Maximum	Unit
t_{CF2CD}	nCONFIG low to CONF_DONE low	—	600	ns
t_{CF2ST0}	nCONFIG low to nSTATUS low	—	600	ns
t_{CFG}	nCONFIG low pulse width	2	—	μ s

Term	Definition
PLL specifications	<p>Diagram of PLL specifications</p> <p>Legend Reconfigurable in User Mode</p> <p>Note: (1) Core Clock can only be fed by dedicated clock input pins or PLL outputs.</p>
R _L	Receiver differential input discrete resistor (external to the Arria V device).
Sampling window (SW)	<p>Timing diagram—The period of time during which the data must be valid in order to capture it correctly. The setup and hold times determine the ideal strobe position in the sampling window, as shown:</p> <p>Bit Time</p> <p>0.5 x TCCS RSKM Sampling Window (SW) RSKM 0.5 x TCCS</p>

I/O Standard	V _{CCIO} (V)			V _{DIF(DC)} (V)		V _{X(AC)} (V)			V _{CM(DC)} (V)			V _{DIF(AC)} (V)	
	Min	Typ	Max	Min	Max	Min	Typ	Max	Min	Typ	Max	Min	Max
HSTL-12 Class I, II	1.14	1.2	1.26	0.16	V _{CCIO} + 0.3	—	0.5 × V _{CCIO}	—	0.4 × V _{CCIO}	0.5 × V _{CCIO}	0.6 × V _{CCIO}	0.3	V _{CCIO} + 0.48
HSUL-12	1.14	1.2	1.3	0.26	0.26	0.5 × V _{CCIO} - 0.12	0.5 × V _{CCIO}	0.5 × V _{CCIO} + 0.12	0.4 × V _{CCIO}	0.5 × V _{CCIO}	0.6 × V _{CCIO}	0.44	0.44

Table 2-21: Differential I/O Standard Specifications for Arria V GZ Devices

I/O Standard	V _{CCIO} (V) ⁽¹²⁸⁾			V _{ID} (mV) ⁽¹²⁹⁾			V _{ICM(DC)} (V)			V _{OD} (V) ⁽¹³⁰⁾			V _{OCM} (V) ⁽¹³⁰⁾		
	Min	Typ	Max	Min	Condition	Max	Min	Condition	Max	Min	Typ	Max	Min	Typ	Max
PCML	Transmitter, receiver, and input reference clock pins of the high-speed transceivers use the PCML I/O standard. For transmitter, receiver, and reference clock I/O pin specifications, refer to the "Transceiver Performance Specifications" section.														
2.5 V LVDS ⁽¹³¹⁾	2.375	2.5	2.625	100	V _{CM} = 1.25 V	—	0.05	D _{MAX} ≤ 700 Mbps	1.8	0.247	—	0.6	1.125	1.25	1.375
						—	1.05	D _{MAX} > 700 Mbps	1.55	0.247	—	0.6	1.125	1.25	1.375
BLVDS ⁽¹³²⁾	2.375	2.5	2.625	100	—	—	—	—	—	—	—	—	—	—	—

⁽¹²⁸⁾ Differential inputs are powered by VCCPD which requires 2.5 V.

⁽¹²⁹⁾ The minimum V_{ID} value is applicable over the entire common mode range, V_{CM}.

⁽¹³⁰⁾ RL range: 90 ≤ RL ≤ 110 Ω.

⁽¹³¹⁾ For optimized LVDS receiver performance, the receiver voltage input range must be between 0.25 V to 1.6 V for data rates above 700 Mbps, and 0 V to 1.85 V for data rates below 700 Mbps.

⁽¹³²⁾ There are no fixed V_{ICM}, V_{OD}, and V_{OCM} specifications for BLVDS. They depend on the system topology.

Symbol/Description	Conditions	Transceiver Speed Grade 2			Transceiver Speed Grade 3			Unit
		Min	Typ	Max	Min	Typ	Max	
Differential on-chip termination resistors	85- Ω setting	—	85 \pm 20%	—	—	85 \pm 20%	—	Ω
	100- Ω setting	—	100 \pm 20%	—	—	100 \pm 20%	—	Ω
	120- Ω setting	—	120 \pm 20%	—	—	120 \pm 20%	—	Ω
	150- Ω setting	—	150 \pm 20%	—	—	150 \pm 20%	—	Ω
V _{OCM} (AC coupled)	0.65-V setting	—	650	—	—	650	—	mV
V _{OCM} (DC coupled)	—	—	650	—	—	650	—	mV
Intra-differential pair skew	Tx V _{CM} = 0.5 V and slew rate of 15 ps	—	—	15	—	—	15	ps
Intra-transceiver block transmitter channel-to-channel skew	x6 PMA bonded mode	—	—	120	—	—	120	ps
Inter-transceiver block transmitter channel-to-channel skew	xN PMA bonded mode	—	—	500	—	—	500	ps

Related Information**[Arria V Device Overview](#)**

For more information about device ordering codes.

Symbol/Description	Conditions	Transceiver Speed Grade 2			Transceiver Speed Grade 3			Unit
		Min	Typ	Max	Min	Typ	Max	
Supported data rate range	VCO post-divider L = 2	8000	—	12500	8000	—	10312.5	Mbps
	L = 4	4000	—	6600	4000	—	6600	Mbps
	L = 8 ⁽¹⁵⁵⁾	2000	—	3300	2000	—	3300	Mbps
t _{pll_powerdown} ⁽¹⁵⁶⁾	—	1	—	—	1	—	—	μs
t _{pll_lock} ⁽¹⁵⁷⁾	—	—	—	10	—	—	10	μs

Related Information

- [Arria V Device Overview](#)
For more information about device ordering codes.
- [Transceiver Clocking in Arria V Devices](#)
For more information about clocking ATX PLLs.
- [Dynamic Reconfiguration in Arria V Devices](#)
For more information about reconfiguring ATX PLLs.

Fractional PLL**Table 2-28: Fractional PLL Specifications for Arria V GZ Devices**

Speed grades shown refer to the PMA Speed Grade in the device ordering code. The maximum data rate could be restricted by the Core/PCS speed grade. Contact your Altera Sales Representative for the maximum data rate specifications in each speed grade combination offered. For more information about device ordering codes, refer to the *Arria V Device Overview*.

⁽¹⁵⁵⁾ This clock can be further divided by central or local clock dividers making it possible to use ATX PLL for data rates < 1 Gbps. For more information about ATX PLLs, refer to the Transceiver Clocking in Arria V Devices chapter and the Dynamic Reconfiguration in Arria V Devices chapter.

⁽¹⁵⁶⁾ t_{pll_powerdown} is the PLL powerdown minimum pulse width.

⁽¹⁵⁷⁾ t_{pll_lock} is the time required for the transmitter CMU/ATX PLL to lock to the input reference clock frequency after coming out of reset.

Description	Min	Typ	Max	Unit
Diode ideality factor	1.006	1.008	1.010	—

Periphery Performance

I/O performance supports several system interfaces, such as the **LVDS** high-speed I/O interface, external memory interface, and the **PCI/PCI-X** bus interface. General-purpose I/O standards such as 3.3-, 2.5-, 1.8-, and 1.5-**LVTTL/LVCMOS** are capable of a typical 167 MHz and 1.2-**LVCMOS** at 100 MHz interfacing frequency with a 10 pF load.

Note: The actual achievable frequency depends on design- and system-specific factors. Ensure proper timing closure in your design and perform HSPICE/IBIS simulations based on your specific design and system setup to determine the maximum achievable frequency in your system.

High-Speed I/O Specification

High-Speed Clock Specifications

Table 2-39: High-Speed Clock Specifications for Arria V GZ Devices

When J = 3 to 10, use the serializer/deserializer (SERDES) block.

When J = 1 or 2, bypass the SERDES block.

For LVDS applications, you must use the PLLs in integer PLL mode.

Arria V GZ devices support the following output standards using true LVDS output buffer types on all I/O banks.

- True RSDS output standard with data rates of up to 230 Mbps
- True mini-LVDS output standard with data rates of up to 340 Mbps

Symbol	Conditions	C3, I3L			C4, I4			Unit
		Min	Typ	Max	Min	Typ	Max	
True Differential I/O Standards - $f_{\text{HSDR DPA}}$ (data rate)	SERDES factor J = 3 to 10 (192), (193), (194), (195), (196), (197)	150	—	1250	150	—	1050	Mbps
	SERDES factor J ≥ 4 LVDS RX with DPA (193), (195), (196), (197)	150	—	1600	150	—	1250	Mbps
	SERDES factor J = 2, uses DDR Registers	(198)	—	(199)	(198)	—	(199)	Mbps
	SERDES factor J = 1, uses SDR Register	(198)	—	(199)	(198)	—	(199)	Mbps
f_{HSDR} (data rate)	SERDES factor J = 3 to 10	(198)	—	(200)	(198)	—	(200)	Mbps
	SERDES factor J = 2, uses DDR Registers	(198)	—	(199)	(198)	—	(199)	Mbps
	SERDES factor J = 1, uses SDR Register	(198)	—	(199)	(198)	—	(199)	Mbps

(192) The F_{MAX} specification is based on the fast clock used for serial data. The interface F_{MAX} is also dependent on the parallel clock domain which is design dependent and requires timing analysis.

(193) Arria V GZ RX LVDS will need DPA. For Arria V GZ TX LVDS, the receiver side component must have DPA.

(194) Arria V GZ LVDS serialization and de-serialization factor needs to be x4 and above.

(195) Requires package skew compensation with PCB trace length.

(196) Do not mix single-ended I/O buffer within LVDS I/O bank.

(197) Chip-to-chip communication only with a maximum load of 5 pF.

(198) The minimum specification depends on the clock source (for example, the PLL and clock pin) and the clock routing resource (global, regional, or local) that you use. The I/O differential buffer and input register do not have a minimum toggle rate.

(199) The maximum ideal data rate is the SERDES factor (J) x the PLL maximum output frequency (f_{OUT}) provided you can close the design timing and the signal integrity simulation is clean.

(200) You can estimate the achievable maximum data rate for non-DPA mode by performing link timing closure analysis. You must consider the board skew margin, transmitter delay margin, and receiver sampling margin to determine the maximum data rate supported.

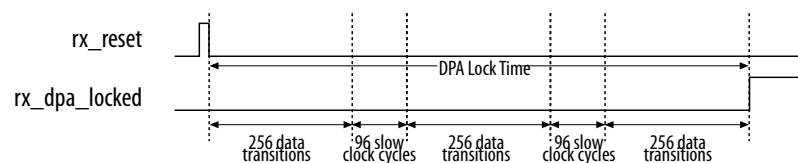
DPA Mode High-Speed I/O Specifications

Table 2-42: High-Speed I/O Specifications for Arria V GZ Devices

When J = 3 to 10, use the serializer/deserializer (SERDES) block.

When J = 1 or 2, bypass the SERDES block.

Symbol	Conditions	C3, I3L			C4, I4			Unit
		Min	Typ	Max	Min	Typ	Max	
DPA run length	—	—	—	10000	—	—	10000	UI

Figure 2-3: DPA Lock Time Specification with DPA PLL Calibration Enabled**Table 2-43: DPA Lock Time Specifications for Arria V GZ Devices**

The DPA lock time is for one channel.

One data transition is defined as a 0-to-1 or 1-to-0 transition.

The DPA lock time stated in this table applies to both commercial and industrial grade.

Standard	Training Pattern	Number of Data Transitions in One Repetition of the Training Pattern	Number of Repetitions per 256 Data Transitions ⁽²⁰¹⁾	Maximum
SPI-4	00000000001111111111	2	128	640 data transitions

⁽²⁰¹⁾ This is the number of repetitions for the stated training pattern to achieve the 256 data transitions.

DLL Range Specifications

Table 2-47: DLL Range Specifications for Arria V GZ Devices

Arria V GZ devices support memory interface frequencies lower than 300 MHz, although the reference clock that feeds the DLL must be at least 300 MHz. To support interfaces below 300 MHz, multiply the reference clock feeding the DLL to ensure the frequency is within the supported range of the DLL.

Parameter	C3, I3L	C4, I4	Unit
DLL operating frequency range	300 – 890	300 – 890	MHz

DQS Logic Block Specifications

Table 2-48: DQS Phase Offset Delay Per Setting for Arria V GZ Devices

The typical value equals the average of the minimum and maximum values.

The delay settings are linear with a cumulative delay variation of 40 ps for all speed grades. For example, when using a –3 speed grade and applying a 10-phase offset setting to a 90° phase shift at 400 MHz, the expected average cumulative delay is $[625 \text{ ps} + (10 \times 11 \text{ ps}) \pm 20 \text{ ps}] = 735 \text{ ps} \pm 20 \text{ ps}$.

Speed Grade	Min	Max	Unit
C3, I3L	8	15	ps
C4, I4	8	16	ps

Table 2-49: DQS Phase Shift Error Specification for DLL-Delayed Clock ($t_{\text{DQS_PSERR}}$) for Arria V GZ Devices

This error specification is the absolute maximum and minimum error. For example, skew on three DQS delay buffers in a –3 speed grade is $\pm 84 \text{ ps}$ or $\pm 42 \text{ ps}$.

Number of DQS Delay Buffers	C3, I3L	C4, I4	Unit
1	30	32	ps
2	60	64	ps
3	90	96	ps

Term	Definition
t_C	High-speed receiver and transmitter input and output clock period.
TCCS (channel-to-channel-skew)	The timing difference between the fastest and slowest output edges, including t_{CO} variation and clock skew, across channels driven by the same PLL. The clock is included in the TCCS measurement (refer to the Timing Diagram figure under SW in this table).
t_{DUTY}	High-speed I/O block—Duty cycle on the high-speed transmitter output clock.
t_{FALL}	Signal high-to-low transition time (80-20%)
t_{INCCJ}	Cycle-to-cycle jitter tolerance on the PLL clock input.
t_{OUTPJ_IO}	Period jitter on the general purpose I/O driven by a PLL.
t_{OUTPJ_DC}	Period jitter on the dedicated clock output driven by a PLL.
t_{RISE}	Signal low-to-high transition time (20-80%)
Timing Unit Interval (TUI)	The timing budget allowed for skew, propagation delays, and the data sampling window. ($TUI = 1/(\text{receiver input clock frequency multiplication factor}) = t_C/w$)
$V_{CM(DC)}$	DC common mode input voltage.
V_{ICM}	Input common mode voltage—The common mode of the differential signal at the receiver.
V_{ID}	Input differential voltage swing—The difference in voltage between the positive and complementary conductors of a differential transmission at the receiver.
$V_{DIF(AC)}$	AC differential input voltage—Minimum AC input differential voltage required for switching.
$V_{DIF(DC)}$	DC differential input voltage— Minimum DC input differential voltage required for switching.
V_{IH}	Voltage input high—The minimum positive voltage applied to the input which is accepted by the device as a logic high.
$V_{IH(AC)}$	High-level AC input voltage
$V_{IH(DC)}$	High-level DC input voltage
V_{IL}	Voltage input low—The maximum positive voltage applied to the input which is accepted by the device as a logic low.
$V_{IL(AC)}$	Low-level AC input voltage
$V_{IL(DC)}$	Low-level DC input voltage

Term	Definition
V_{OCM}	Output common mode voltage—The common mode of the differential signal at the transmitter.
V_{OD}	Output differential voltage swing—The difference in voltage between the positive and complementary conductors of a differential transmission at the transmitter.
V_{SWING}	Differential input voltage
V_X	Input differential cross point voltage
V_{OX}	Output differential cross point voltage
W	High-speed I/O block—clock boost factor

Document Revision History

Date	Version	Changes
February 2017	2017.02.10	<ul style="list-style-type: none"> Changed the minimum value for t_{CD2UMC} in the "FPP Timing Parameters for Arria V GZ Devices When the DCLK-to-DATA[] Ratio is 1" table. Changed the minimum value for t_{CD2UMC} in the "FPP Timing Parameters for Arria V GZ Devices When the DCLK-to-DATA[] Ratio is >1" table. Changed the minimum value for t_{CD2UMC} in the "AS Timing Parameters for AS x1 and AS x4 Configurations in Arria V GZ Devices" table. Changed the minimum value for t_{CD2UMC} in the "PS Timing Parameters for Arria V GZ Devices" table. Changed the minimum number of clock cycles value in the "Initialization Clock Source Option and the Maximum Frequency for Arria V GZ Devices" table.